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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s):	Casebolt, Matthew P.; Ogrey, Robert E.
Assignee:	VA Linux Systems, Inc.
Title:	Computer System For Highly-Dense Mounting Of System Components
Serial No.:	09/370,121 Filing Date: August 6, 1999
Examiner:	Y. Chang Group Art Unit: 2835
Docket No.:	M-7792 US
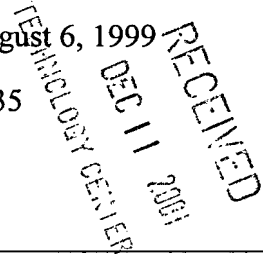
Newport Beach, California
November 15, 2001

BOX NON-FEE AMENDMENT
COMMISSIONER FOR PATENTS
Washington, D. C. 20231

RESPONSE TO NON-FINAL OFFICE ACTION OF AUGUST 15, 2001

Dear Sir:

In response to the Office Action of August 15, 2001, please amend the above-referenced application as follows.

IN THE SPECIFICATION

Please replace the second paragraph on page 4, starting on line 10, with the following paragraph:

Another limiting factor with high-end computing systems is ensuring effective heat dissipation from the various hardware components. In particular, the central processing unit and the electrical components mounted on the various circuit boards in the computer system generate large amounts of heat. Without proper cooling, these components can fail or can cause other components mechanisms to fail. One conventional method of cooling these components is the use of a fan mounted on a side of the chassis to force air to flow from outside the chassis into and over the circuit boards. In a given chassis, this method is effective when the number and size of the components to be cooled are small. However, as more and more components are squeezed into smaller server cases, it becomes increasingly